

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SS00-ZZ-0003

Description : SFP+ Connector

Right Angle;SMT

Contact Area : 30μ" Min. Gold

Packing with Tape Reel

100% RoHS material ,without exemption



Halogen
Free

Spec No.
SS0022007-00

Update Date
2022/12/2

Revision
A

Approved	Checked	Prepared



湧德電子 股份有限公司
UDE Corp.

桃園市(33852) 蘆竹區內溪路 68 巷13號

No.13, Ln. 68, Neixi Rd., Luzhu Dist., Taoyuan City (33852), Taiwan

TEL: 886-3-3242000 FAX: 886-3-3246611

<http://www.ude-corp.com/>

Revision History

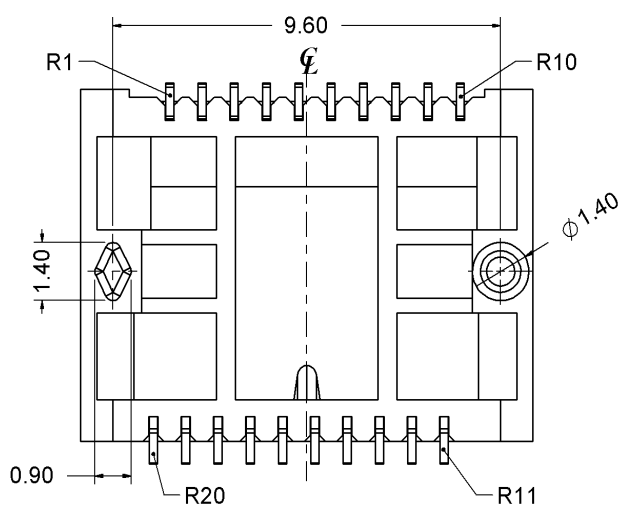
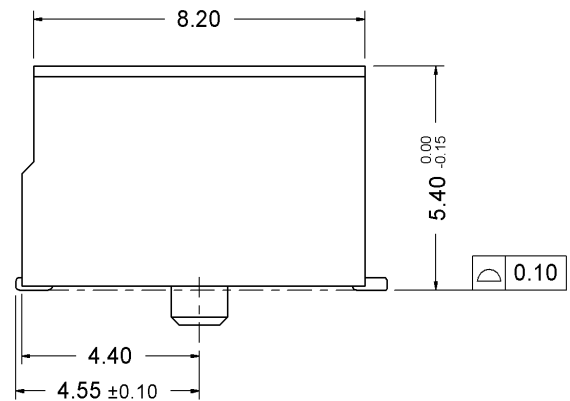
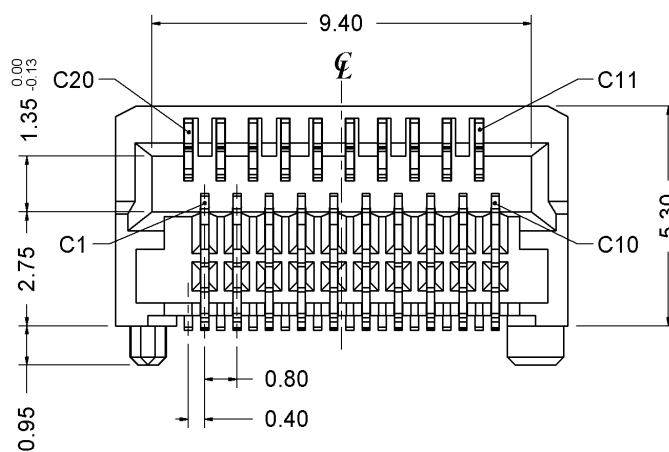
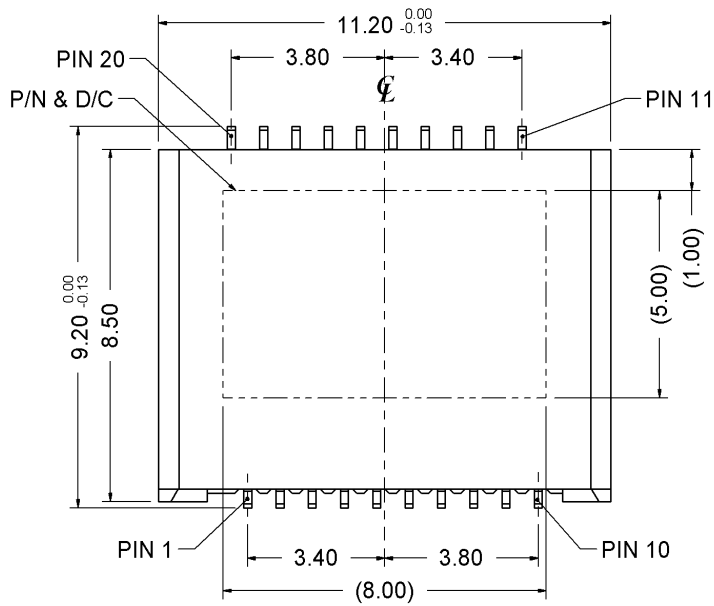
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1. MECHANICAL DIMENSION

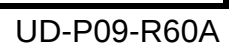
Product Dimension

Unit:mm

General Tolerance : X.X : ± 0.25
 X.XX : ± 0.13



All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified



2. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Terminal Parts (Underplating : 50μ" min. Nickel overall)

Terminal : PH. Bronze, Thickness=0.20mm

Finish : Contact Area : 30μ" Gold

Solder Tail : 100μ" min. Matte Tin

Plastic Parts

Housing : LCP, Black <UL94V-0>

3. Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : -55°C to +105°C

4. SFP 1X Connector specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 1000MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

5. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

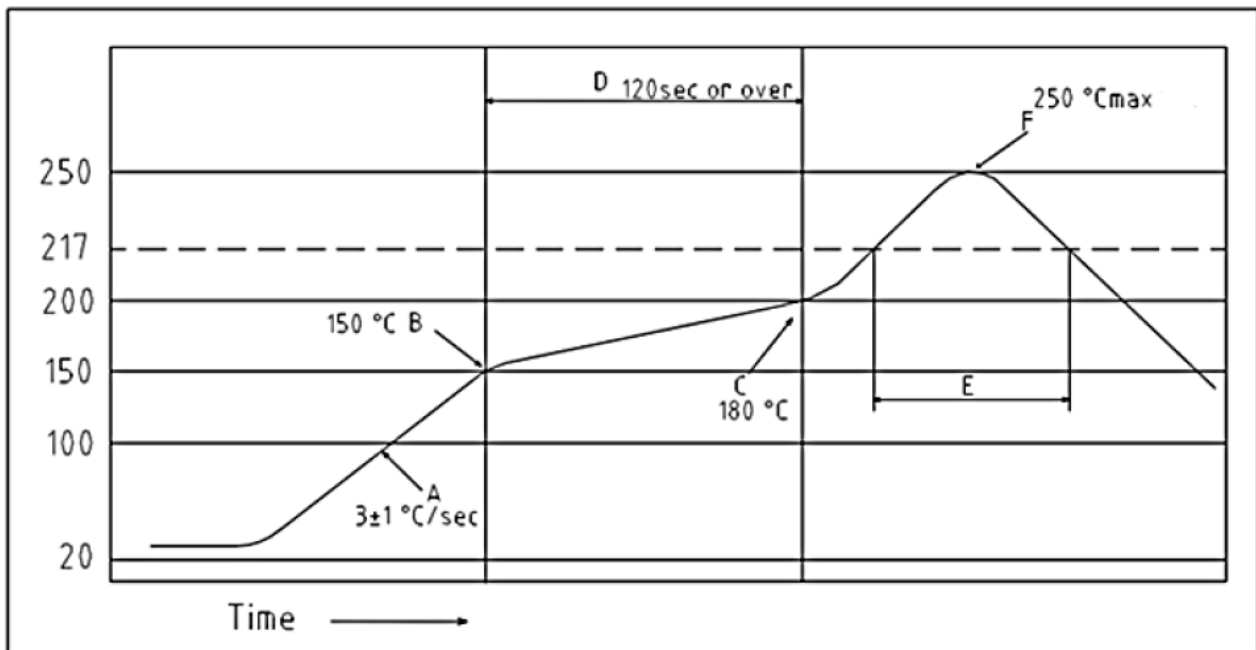
6. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

7. IR REFLOW TEMPERATURE PROFILE

Temperature condition of reflow soldering

Contents	Soldering Condition
A : Increasing speed	$3\pm 1^{\circ}\text{C}/\text{sec}$
B : Pre-heat starting Temp	150°C
C : Pre-heat ending Temp	180°C
D : Pre-heat interval	120 sec or over
E : Over 217°C time	60~150 sec
F : Peak Temperature	250°C max. 10sec



Type of lead-free solder should be 96.5Sn-3.0Ag-0.5Cu or 99.3Sn-0.7Cu.